

ABSTRACT OF THE DISCLOSURE
METHOD FOR THE MAKING OF SOLDER CONNECTION PADS ON A
SUBSTRATE AND GUIDE FOR THE IMPLEMENTATION OF THE METHOD

A method for molding and soldering electrical connection pads to the
5 electrical connection-receiving zones of electronic components or circuits
comprises an operation for the injection of conductive liquid alloy into a guide open
at one end placed so as to face the connection-receiving zone of the component.
The guide is formed by two separable parts, a mold and an injection matrix, the
mold and the injection matrix comprising passages, with a narrowing of the guide at
10 the level of the separation of the parts, and the parts of the guide are separated
while the alloy is in the liquid state. Applications: making of connection pads for
substrates or electronic components.

Figure 8

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